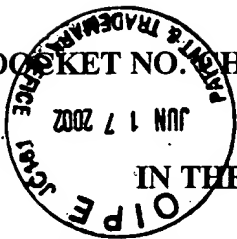


DOCKET NO. CHITTIPEDDI 59-108



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sailesh Chittipeddi, *et al.*

Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

Commissioner for Patents
Washington, D. C. 20231

Sir:

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on June 11, 2002 (Date)

Elizabeth C. Ramirez
(Printed or typed name of person signing the certificate)

Elizabeth C. Ramirez
(Signature of the person signing the certificate)

June 11, 2002
(Date of Signature)

INFORMATION DISCLOSURE STATEMENT

In accordance with 37 C.F.R. §1.56 and the provisions of 37 C.F.R. §§1.97 and 1.98 and §609 of the Manual of Patent Examining Procedure, Applicant hereby makes a disclosure of the patents, publications and other information listed below and on the accompanying form PTO-1449, which may be potentially material to the patentability of the invention disclosed in the above-referenced application. Pursuant to § 1.97(e) the Applicant hereby states that each item of information contained in the information disclosure statement was cited in a communication from

2823
PATENT
RECEIVED #19
JUN 19 2002
J. Williams
8/22/02
TC 2800 MAIL ROOM

a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

<u>U.S. Patent No.</u>	<u>Inventor</u>	<u>Date</u>
4,622,576	Buynoski	November 11, 1986
5,455,195	Ramsey et al.	October 3, 1995

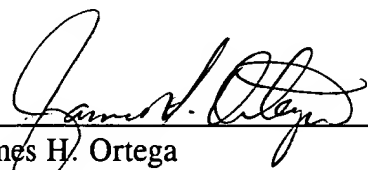
<u>Foreign Patent No.</u>	<u>Country</u>	<u>Date</u>
903,476	GB	Aug. 15, 1962
1,294,770	GB	1 Nov. 1972
WO 00/59029	PCT	10/05/00
JP1-255234	JP	1989-10-12
JP62-216339	JP	1987-09-22

Applicant hereby certifies that each item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the statement.

As attorney for the Applicant, I am signing below on the basis of the information supplied by an individual designated in § 1.56(c).

Respectfully submitted,

HITT GAINES & BOISBRUN, P.C.



James H. Ortega
Registration No. 50,554

Date: June 11, 2002
Hitt Gaines & Boisbrun, P.C.
P.O. Box 832570
Richardson, Texas 75083
(972) 480-8800